

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XCL213xxxxDR
Typical mass: 25.0 mg

Part	Part name	Weight(mg)	Material name	Ratio(ppm)	CAS №
Coil	Core (Ferrite)	6.576	Iron oxide	263000	1309-37-1
		1.280	Zinc oxide	51200	1314-13-2
		1.042	Nickel oxide	41700	1313-99-1
		0.336	Copper oxide	13500	1317-38-0
		0.054	Tin oxide	2200	18282-10-5
	Internal conductor	0.336	Silver	13500	7440-22-4
	Electrode	0.401	Silver	16100	7440-22-4
		0.076	Nickel	3000	7440-02-0
	0.206	Tin	8200	7440-31-5	
Pb-free solder	Pb-free solder	0.876	Tin	35000	7440-31-5
		0.046	Antimony	1900	7440-36-0
IC	Silicon chip	0.648	Silicon	25900	7440-21-3
			- Arsenic	<1	7440-38-2
	Lead pad	1.354	Nickel	54100	7440-02-0
		0.129	Silver	5200	7440-22-4
		0.015	Gold	600	7440-57-5
	Die attach	0.208	Silver	8300	7440-22-4
		0.031	Epoxy resin	1200	-
	Bonding wire	0.208	Gold	8300	7440-57-5
	Resin	10.021	Silica	400900	60676-86-0
		0.531	Epoxy resin	21200	-
		0.354	Phenol resin	14100	-
	0.236	Metal hydroxide	9400	-	
	0.035	Silica, crystalline	1400	14808-60-7	

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."